

### Claims

Claims 1-11 (canceled)

12. (currently amended) An electronic package comprising:

a device carrier including a metal surface;

at least a semiconductor unit including at least an electrode; and

at least an interconnection portion including a first part and a second part, wherein said second part directly contacts said metal surface and said semiconductor unit, both said first part and said second part span ~~spanning~~ between and tie together said metal surface and said semiconductor unit, ~~said second part spanning between said metal surface and the electrode of said semiconductor unit,~~ said second part is ~~being~~ wrapped by said first part, said first part has ~~having~~ a melting point lower than that of said second part, and said first part adheres ~~adhering~~ to said second part.

13. (original) The electronic package according to claim 12 wherein said interconnection portion electrically connects said metal surface and said semiconductor unit.

14. (original) The electronic package according to claim 12 wherein said interconnection portion mechanically connects said device carrier and said semiconductor unit.

15. (original) The electronic package according to claim 12 wherein said first part contains more tin than lead, while said second part contains more lead than tin.

16. (original) The electronic package according to claim 12 wherein said device carrier is a lead frame.

17. (previously presented) The electronic package according to claim 12 wherein said device carrier is a lead frame enclosed by said metal surface.

18. (previously presented) The electronic package according to claim 12 wherein said second part is sealed by said first part, said device carrier, and said semiconductor unit.

19. (previously presented) The electronic package according to claim 12 wherein said first part contains materials by which the solder wettability between said first part and said second part is controlled by said second part.

20. (previously presented) The electronic package according to claim 12 wherein said first part has an end partially contacting the electrode of said semiconductor unit and partially contacting an area which is part of said semiconductor unit and which surrounds the electrode of said semiconductor unit.